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(12) **United States Design Patent**
Kouzuma et al.

(10) **Patent No.: US D900,760 S**
(45) **Date of Patent: ** Nov. 3, 2020**

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(54) **ION SHIELD PLATE FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

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(73) Assignee: **Hitachi High-Tech Corporation**, Tokyo (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/677,753**

(22) Filed: **Jan. 23, 2019**

(30) **Foreign Application Priority Data**

Jul. 24, 2018 (JP) 2018-016190

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/184**; D26/138; D23/261; D15/126

(58) **Field of Classification Search**
USPC D13/184; D26/1, 24, 74, 72, 36, 59, 118, D26/133, 134, 261; D15/126
CPC H01R 5/00; H01R 13/46; H01R 13/514; H01R 31/02; F21V 5/00; H01J 19/54; H01J 5/48; H01J 1/02; H01J 5/16; H01J 5/00; H01J 5/50; H01L 33/642; H01L 33/643; H01L 33/644
See application file for complete search history.

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Primary Examiner — Janice Hallmark
Assistant Examiner — Harold E Blackwell, II
(74) *Attorney, Agent, or Firm* — Crowell & Moring LLP

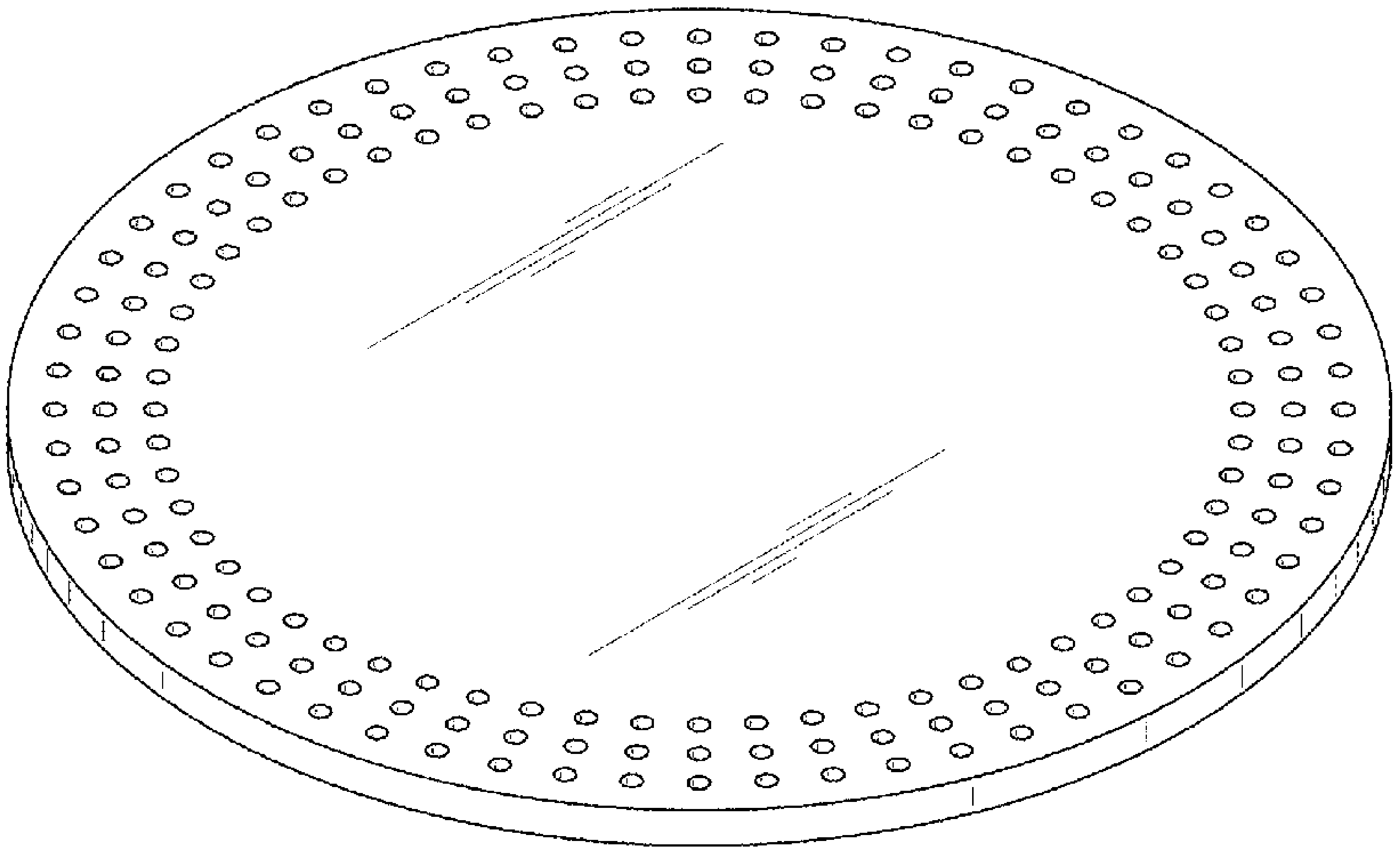
(57) **CLAIM**

The ornamental design for an ion shield plate for semiconductor manufacturing apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a front, bottom and right side perspective view of an ion shield plate for semiconductor manufacturing apparatus according to the design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a left side elevational view thereof;
FIG. **4** is a right side elevational view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof;
FIG. **7** is a rear elevational view thereof; and,
FIG. **8** is a cross-sectional view taken along line **8**-**8** of FIG. **2**.

1 Claim, 3 Drawing Sheets



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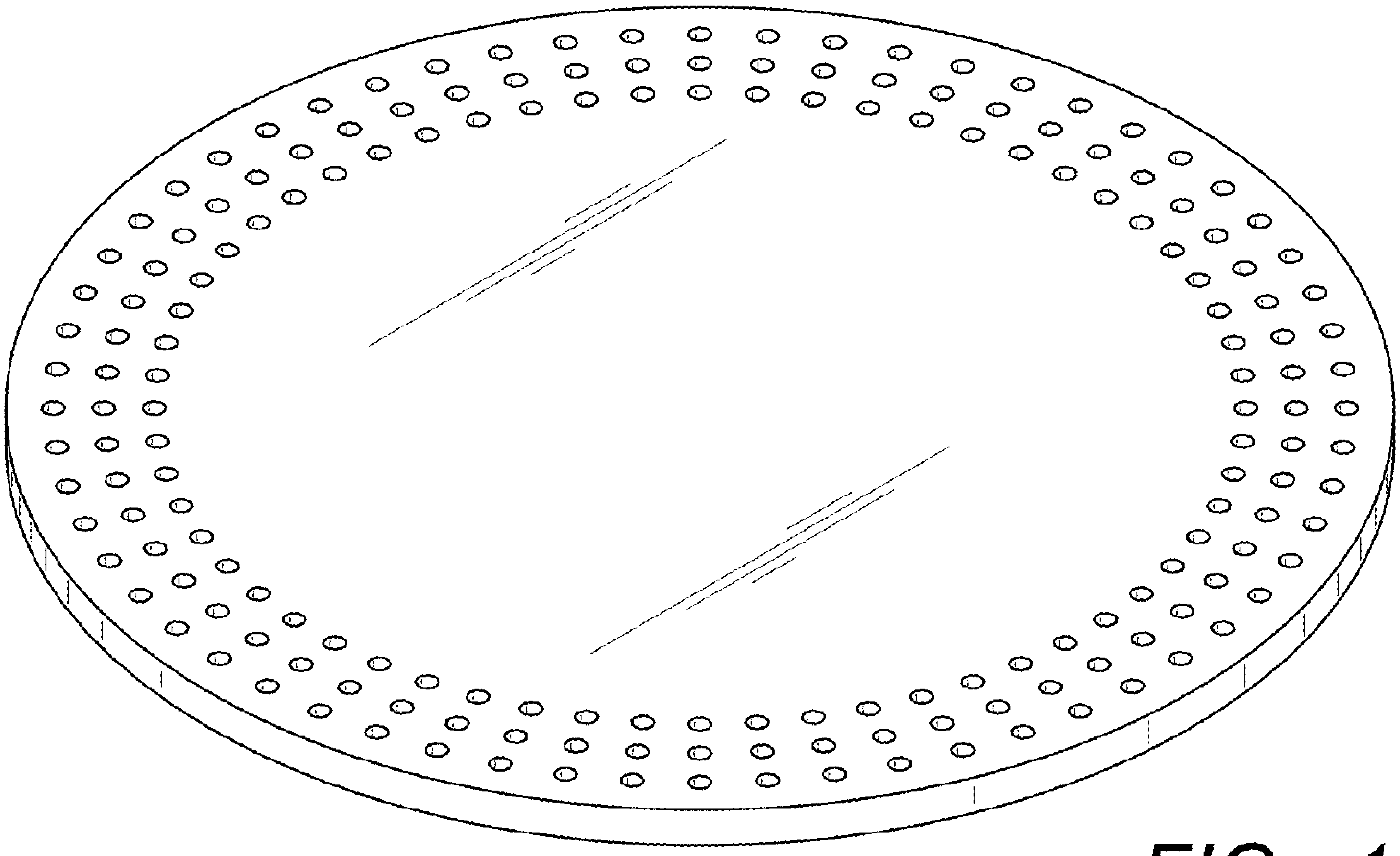

FIG. 1

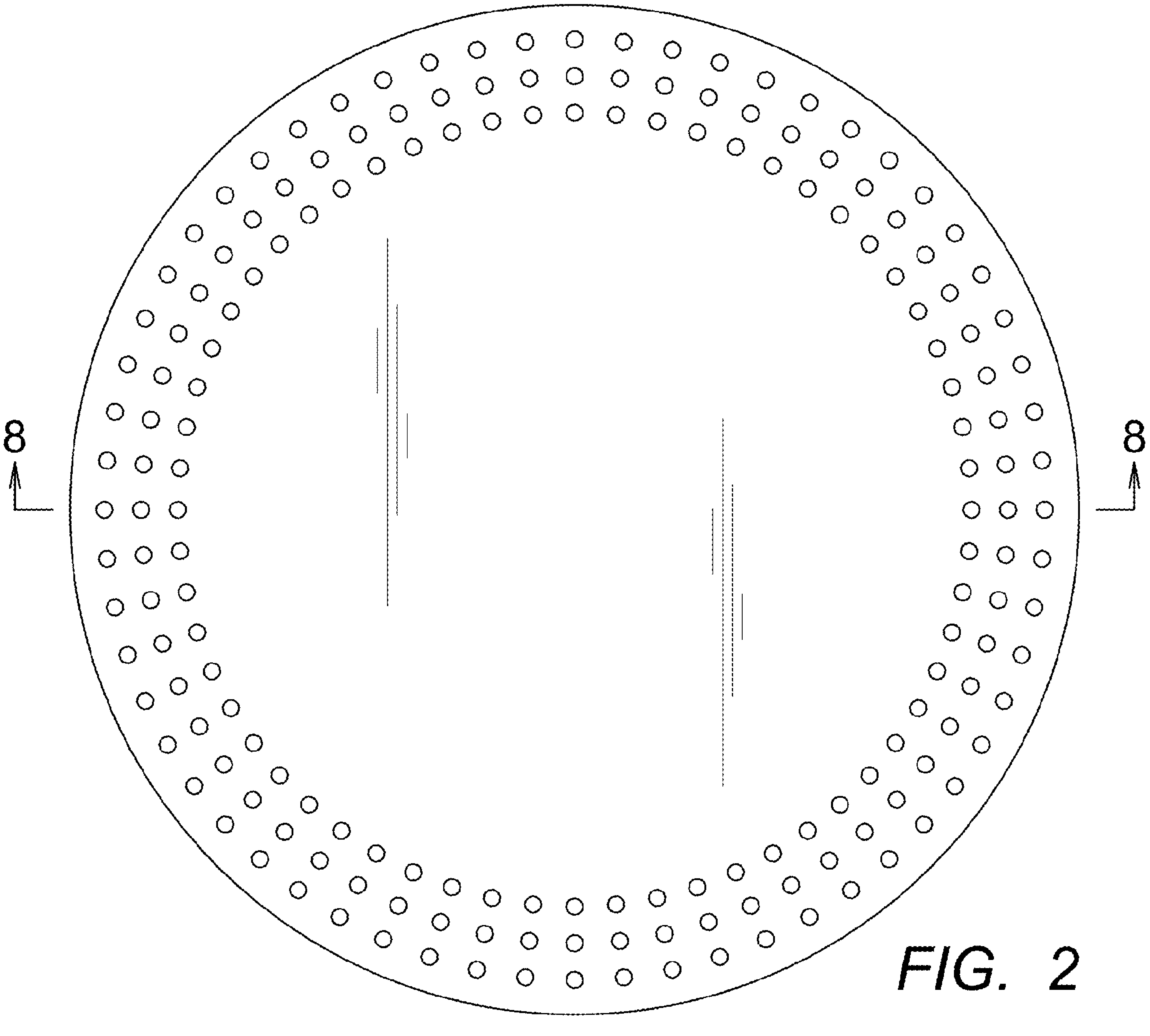

FIG. 2

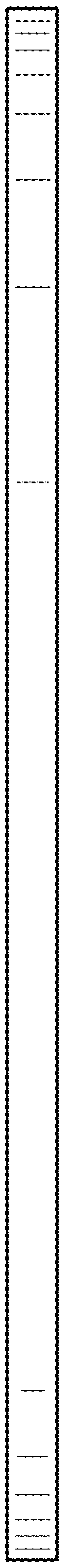

FIG. 3

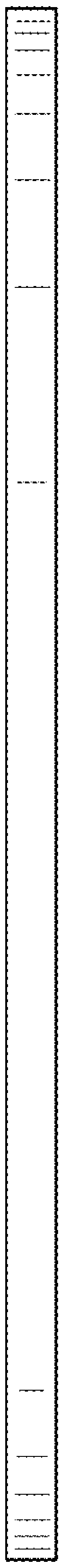

FIG. 4

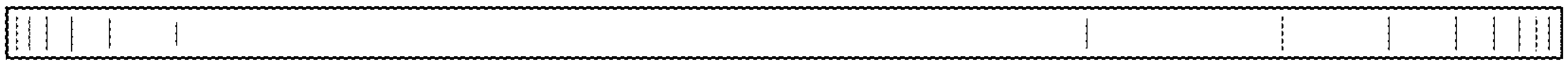

FIG. 5

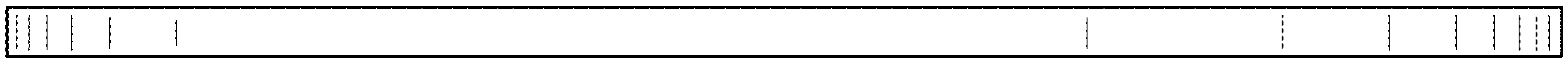

FIG. 6

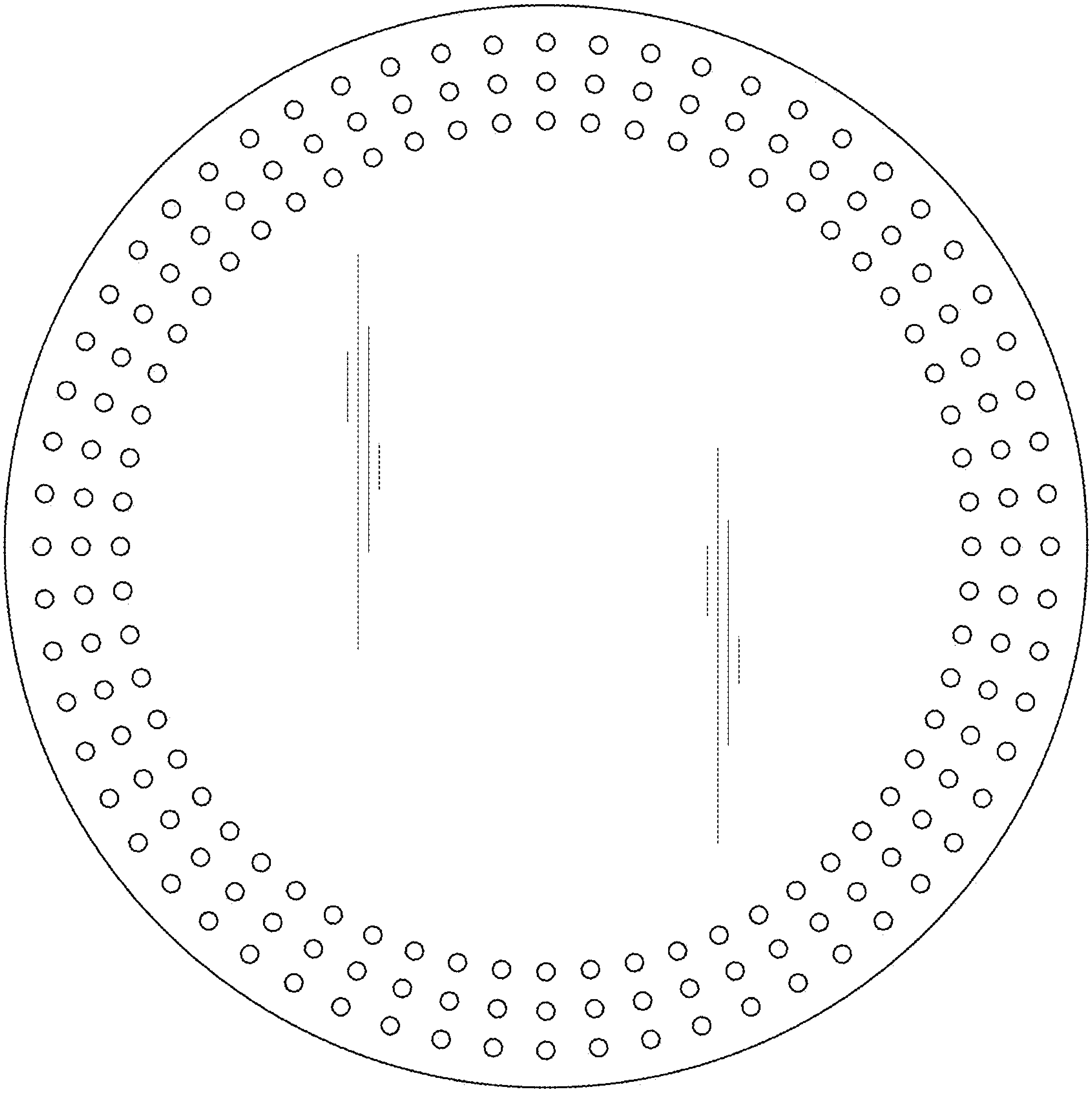

FIG. 7

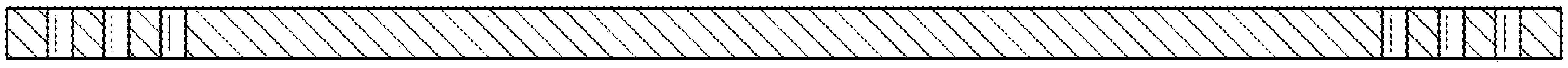

FIG. 8

UNITED STATES PATENT AND TRADEMARK OFFICE

CERTIFICATE OF CORRECTION

PATENT NO. : D900,760 S
APPLICATION NO. : 29/677753
DATED : November 3, 2020
INVENTOR(S) : Yutaka Kouzuma et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the Title Page

Item (71), should read: -- Hitachi High-Tech Corporation --.

Signed and Sealed this
Second Day of March, 2021

Drew Hirshfeld
Performing the Functions and Duties of the
Under Secretary of Commerce for Intellectual Property and
Director of the United States Patent and Trademark Office